

Electronic Patent Application Fee Transmittal				
Application Number:		10049270		
Filing Date:		27-Jun-2002		
Title of Invention:		MULTILAYER PRINTED WIRING BOARD, SOLDER RESIST COMPOSITION, METHOD FOR MANUFACTURING MULTILAYER PRINTED WIRING BOARD, AND SEMICONDUCTOR DEVICE		
First Named Inventor/Applicant Name:		Hui Zhong		
Filer:		Marvin Jay Spivak/Igmar Sorto		
Attorney Docket Number:		312302US40PCT		
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180